

PIC-based spectroscopic chemical sensing

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ABSTRACT

Photothermal sensing is an indirect absorption sensing method that measures the change in temperature caused by the analyte molecules absorbing at a particular wavelength. While this technique has been demonstrated on various photonic platforms, silicon nitride circuits are specifically known for their ultralow propagation losses and CMOS compatibility. Here, we demonstrate suspended silicon nitride microdisk resonators that can be employed for near-infrared photothermal sensing. The photonic circuits were made in a photonic foundry multi-project wafer run with simple post-processing to remove the oxide underneath the microdisk. We observed optical bistability in our suspended microdisks, making them suitable for the required application.

Keywords: sensing, integrated photonics, spectroscopy, silicon photonics

1. INTRODUCTION

Infrared absorption sensing is a well-known technique used to probe the concentration of various substances by excitation of their vibrational modes. Photonic integrated circuits (PICs) have enabled the production of chip-scale sensors to reduce their size, weight, and power consumption (SWaP) properties. Chip-scale chemical sensors based on optical waveguides^{1–21}, interferometers^{22–25}, as well as optical resonators^{26–33} have been intensively investigated. However, direct absorption-based sensing is susceptible to interference caused by scattering and reflections of molecules and waveguide roughness². Alternatively, photothermal sensing (PTS) is an indirect technique that measures the rise in temperature from the absorption of a pump laser by monitoring the shift in the cavity resonant wavelength of the probe laser.

PTS has been demonstrated on several photonic platforms, including silicon-on-insulator (SOI)³⁴, thin-film lithium niobate (TFLN)³⁵, chalcogenide glasses³⁶, and silicon nitride³⁷. Theoretical calculations show that the PTS enhancement factor, defined as the ratio of change in power of the probe beam to the pump beam, is proportional to the Q-factor of the resonant cavity^{30,38}. Silicon nitride photonics have demonstrated remarkably low loss and high-Q resonators exceeding 100 million^{39,40}, making them a suitable candidate for PTS. Moreover, silicon nitride is CMOS compatible and is included in the process design kit (PDK) of major PIC foundries. Additionally, suspended structures have shown improved sensitivity for PTS owing to their lower thermal conductivity. Among the photonic components employed for PTS, microdisks can be easily suspended by anchoring them with bottom cladding around the center, which does not overlap with the optical mode residing near the disk edge.

Here, we report a suspended silicon nitride microdisk resonator fabricated using a multi-project wafer (MPW) run by AIM Photonics foundry⁴¹. The microdisk was characterized both before and after the suspension process. We discuss the chip design and post-processing steps required to suspend the microdisk.

2. DESIGN OF MICRODISK RESONATOR

The microdisk was designed on a passive low-loss silicon nitride (SiN) PDK offered by AIM Photonics. Figure 1(a) shows the wafer stack profile consisting of two 220 nm SiN layers separated by 100 nm silica. The top nitride layer serves as an etch stop for removing the top oxide to create the sensing trench. This sensing trench was placed on all the microdisks to enable interaction of the evanescent field with analyte species and to undercut the bottom oxide via wet etching. According

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to the design rules, the minimum dimension of the sensing trench should be $100\text{ }\mu\text{m}$. Therefore, we designed waveguide crossings to act as anchors after the long bus waveguide was fully suspended, as shown in Figures 1(b) and 1(c).

The waveguide crossing dimensions were calculated using the particle swarm optimization algorithm in the Lumerical FDTD solver. Phase matching of the bus waveguide and microdisk resonator fundamental mode is essential to prevent the excitation of higher-order microdisk modes. According to Figure 1(d), the waveguide width and disk radius were chosen to match the effective index of their respective fundamental modes. We designed two microdisks with radii and bus waveguide widths of $65/95\text{ }\mu\text{m}$ and $2/2.25\text{ }\mu\text{m}$, respectively. The coupling gap for the $65\text{ }\mu\text{m}$ disk was kept at $150/300/450\text{ nm}$, and for the $95\text{ }\mu\text{m}$ disk, it was kept at $100/200/300/400/500\text{ nm}$. The bus waveguide was point-coupled to the disk, as pulley coupling would become mechanically unstable after suspension.

The effective indices were calculated using Lumerical MODE simulations for suspended structures with no bottom oxide cladding. The waveguide width for routing was kept standard at $1.5\text{ }\mu\text{m}$, and circular bends with a $95\text{ }\mu\text{m}$ radius were used, as recommended by AIM Photonics. To adiabatically transition to the bus waveguide width, a $30\text{ }\mu\text{m}$ linear taper was used in the region with top oxide cladding. $200\text{ }\mu\text{m}$ inverse tapers with a 475 nm tip width were used as edge couplers. All the components were designed for transverse electric (TE) polarization.

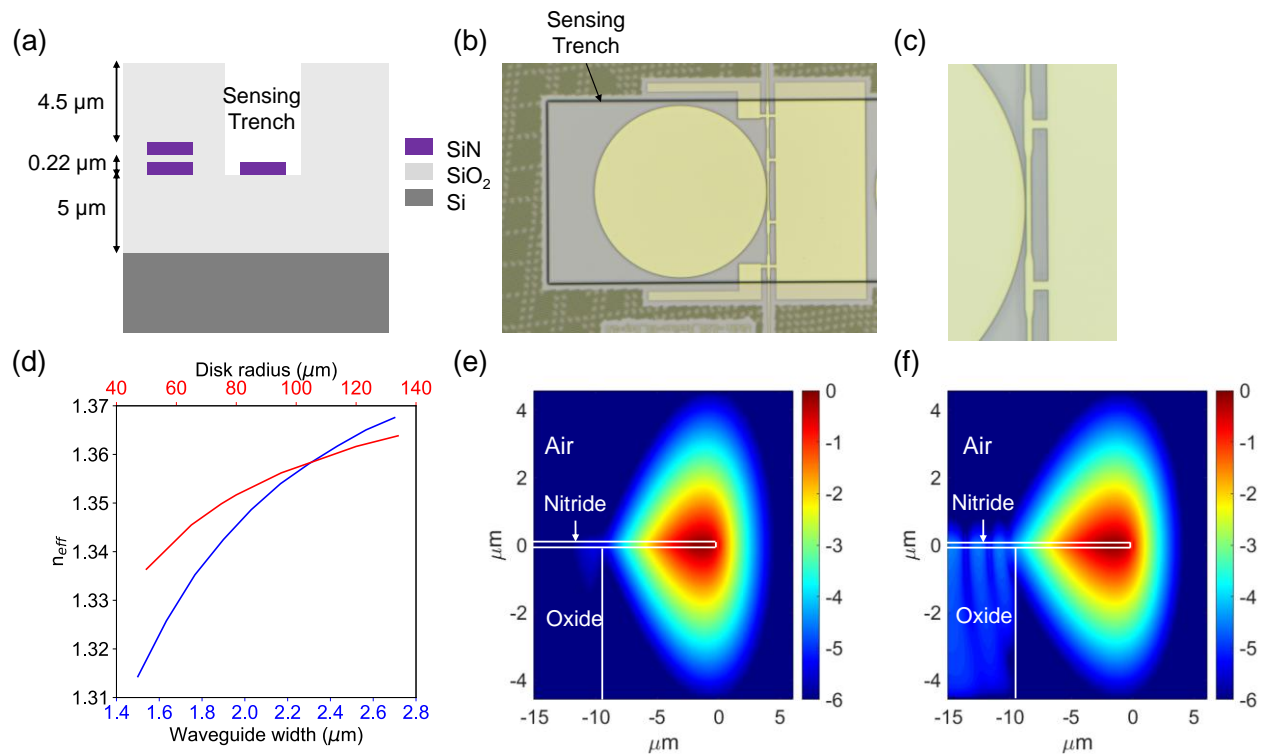


Figure 1. (a) Stack profile of AIM passive low-loss nitride PDK. (b) Microscope image of the fabricated microdisk resonator with radius = $95\text{ }\mu\text{m}$ and coupling gap = 500 nm . (c) Magnified view of the coupling region. (d) The simulated effective index of the fundamental mode in waveguide (blue-line) and microdisk (red-line). Simulated electric field intensity for the microdisk fundamental mode for disk radius equal to (e) $65\text{ }\mu\text{m}$ and (f) $95\text{ }\mu\text{m}$ plotted on a log scale. The origin represents the disk perimeter.

3. FABRICATION OF SUSPENDED MICRODISK

The chips received from AIM Photonics still had bottom oxide (BOX) cladding for the microdisks. To improve the thermal conductivity, we aimed to remove the oxide by using buffered oxide etch (BOE)⁴². Both our simulations and optical measurements indicated that approximately $9.5\text{ }\mu\text{m}$ of undercut is required to minimize leakage of the microdisk fundamental mode into the BOX, which could result in high propagation losses. The entire post-processing process is depicted in Figure 2. First, the entire chip except for the sensing trenches was protected with negative photoresist using direct laser write lithography. The chip was then placed between two Si pieces bonded to a carrier wafer using a photoresist.

A thick photoresist AZ 10XT was carefully dropped on the chip edges using a micropipette to prevent it from flowing into the sensing trenches. Finally, the whole assembly was baked at 110 °C for 20–30 minutes until the thick resist hardened. The carrier wafer was placed in an undiluted 7:1 BOE solution for 95 minutes to undercut 9.5 μm of oxide. After rinsing the wafer in DI water, the chip was immediately transferred to isopropanol without letting it dry. Lastly, the chip was subjected to critical point drying to avoid damage to the suspended structures.

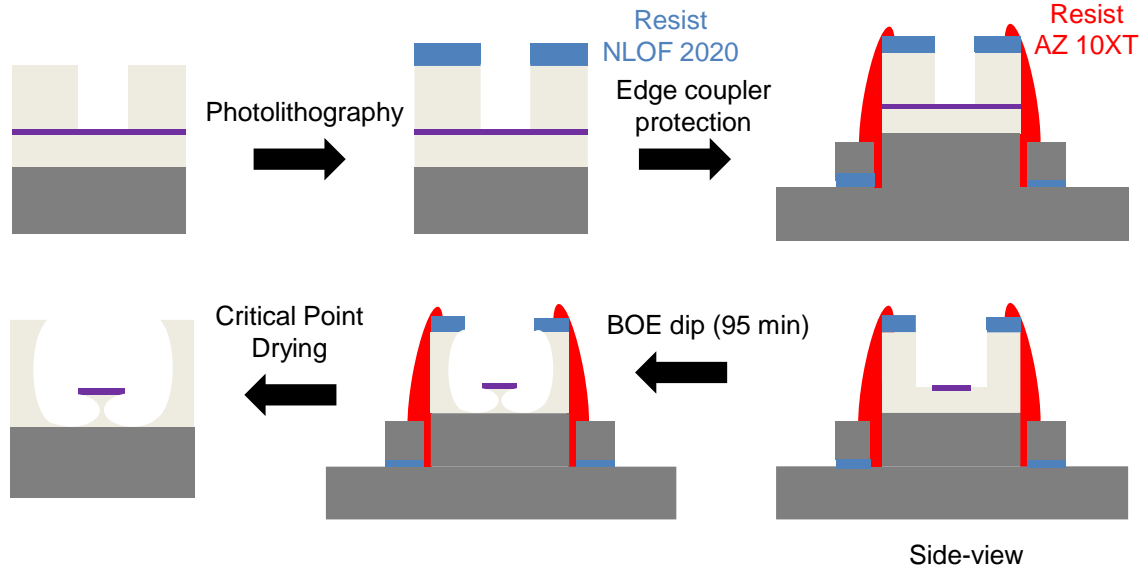


Figure 2. Process flow for suspending the microdisk resonators

4. RESULTS AND DISCUSSION

The microdisks' optical response was measured both before and after the suspension. An optical vector analyzer (OVA, Luna Innovations Inc.) with a built-in external cavity tunable laser was used as the interrogation light source, in conjunction with an erbium-doped fiber amplifier (Amonics Ltd.). The light was coupled in and out of the chip using lensed fibers. Figures 3(a) and 3(d) show the measured microdisk transmission before the suspension for a disk radius of 95 μm and 65 μm , respectively. We observed that the critical coupling condition for the 95 μm disk radius was met around a coupling gap between 400–500 nm, featuring a Q factor of more than 300,000. The propagation loss was estimated between 0.5–0.7 dB/cm. The calculated group index (n_g) from the measured free spectral range (FSR) was 1.742, which closely matched the simulated n_g of 1.758 for the fundamental mode. Radiation losses estimated from the simulations were approximately 0.2 dB/cm due to leakage into the BOX. Figure 3(a) shows the transmission of a highly overcoupled microdisk with a 100 nm coupling gap. We also observed secondary peaks in the spectrum originating from the second-order mode, as its effective index ($n_{\text{eff}} = 1.45$) was very close to that of the fundamental mode ($n_{\text{eff}} = 1.48$). These secondary peaks were not as prominent due to the high radiation losses (~ 20 dB/cm) calculated by simulations. For the 65 μm disk radius, the critical coupling could not be achieved even for a small coupling gap of 150 nm, as shown in Figure 3(d). With a Q-factor of 20k–30k, the propagation loss was estimated between 6–8 dB/cm. The measured n_g (1.726) closely matched the simulated n_g (1.748) for the fundamental mode. The simulated radiation losses were 6 dB/cm. We did not observe any secondary peaks in the transmission as the radiation loss for the second-order mode was extremely high (~ 200 dB/cm).

For suspending the microdisk resonators, we etched the chip in BOE for 35 min, 60 min, and 95 min to undercut approximately 3.5 μm , 6 μm , and 9.5 μm of BOX, respectively. However, no resonant peaks were observed for 3.5 μm and 6 μm etch. We hypothesize that this is due to the mode field overlapping significantly with the undercut BOX/Air interface with high surface roughness. We detected the resonant peaks only after 9.5 μm etch, as shown in Figures 3(b) and 3(c) for disk radii equal to 95 μm and 65 μm , respectively. Even though BOE has a high selectivity for silica compared to SiN, we observed that the nitride layer was also etched to some extent. Figures 3(c) and 3(f) show the SEM images of the coupling region taken after the 9.5 μm undercut. In the case of a 95 μm disk radius, the coupling gap increased from 400 nm to 600 nm, and the waveguide width was reduced from 2.25 μm to 2.11 μm . Similarly, for the 65 μm disk radius, the coupling gap increased from 150 nm to 330 nm, and the waveguide width was reduced from 2 μm to 1.86 μm . This

implied that roughly 70 nm of SiN was etched from the sides. The measured n_g for 95 μm and 65 μm microdisk after suspension were 1.60 and 1.59, which corresponded to a nitride thickness between 150–160 nm according to simulations. Hence, the reduction in thickness was between 60–70 nm.

Around the 1550 nm wavelength, the peak extinction of the 95 μm and 65 μm microdisk resonators was approximately -1 dB and -5 dB, respectively. Moreover, these peaks only appeared for the smallest coupling gaps in both cases. We estimated the propagation loss of the fundamental mode to be around 8 dB/cm and 2 dB/cm for 95 μm and 65 μm disk radius, respectively. These results are opposite to the values obtained before the suspension. Before the suspension, radiation loss was the major contributor to the overall losses in the microdisk, whereas after the suspension, the primary cause of loss arises from the field overlapping with the rough BOX/Air interface. This can also be observed in Figures 1(e) and 1(f), which show the electric field intensity of the fundamental mode on a log scale after undercutting 9.5 μm of oxide. The field overlaps more in the case of the 95 μm disk radius compared to the 65 μm one. The simulations indicate that the 95 μm disk is more susceptible to losses due to the BOX/Air interface, which agrees with our measured values.

The optical characterization indicated that the microdisk design with a starting radius of 65 μm and a 150 nm coupling gap yielded promising resonant peaks after the suspension and was suitable for performing PTS. Figure 4(a) shows the microscope image of a microdisk after suspension. The color change near the circumference of the disk indicates that the BOX underneath has been etched.

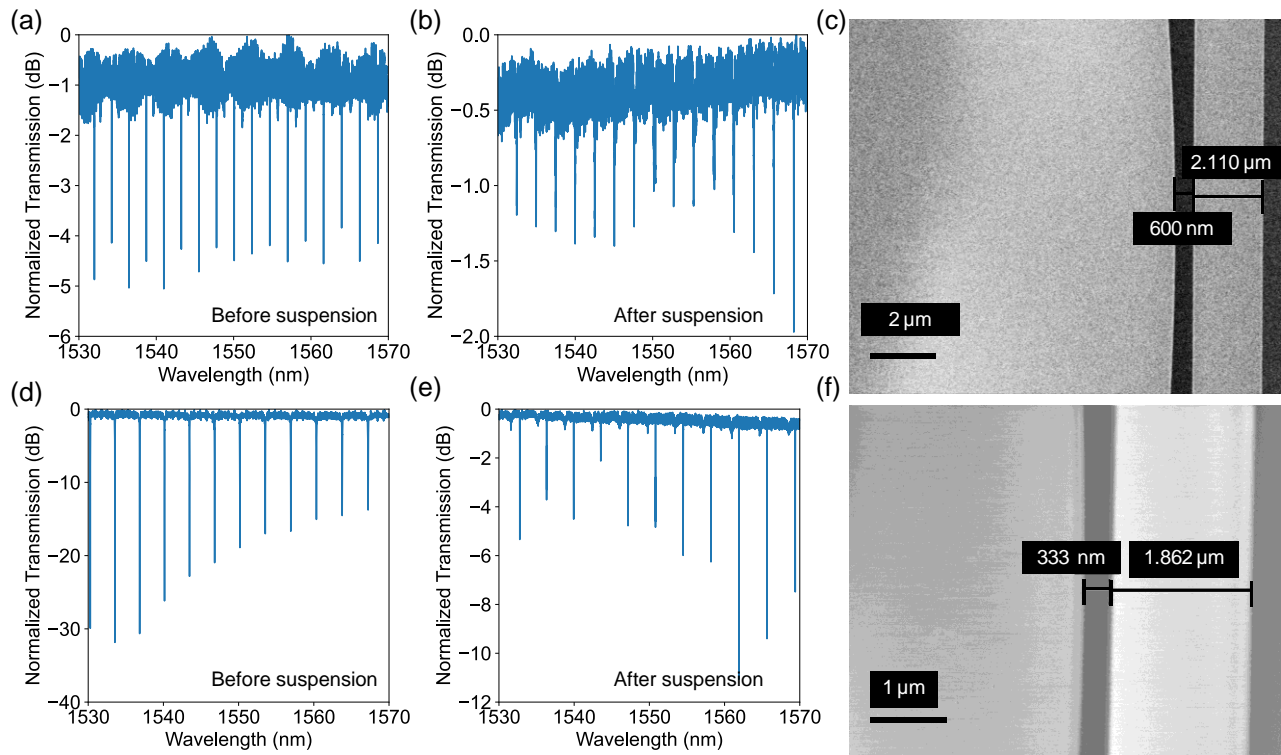


Figure 3. Normalized transmission vs. wavelength for microdisk resonator with radius = 95 μm and coupling gap = 100 nm (a) before suspension and (b) after suspension. (c) SEM image of the microdisk with radius = 95 μm and coupling gap = 100 nm taken after suspension. Normalized transmission vs. wavelength for microdisk resonator with radius = 65 μm and coupling gap = 150 nm (a) before suspension and (b) after suspension. (c) SEM image of the microdisk with radius = 65 μm and coupling gap = 150 nm taken after suspension.

We tested the photothermal properties of the microdisk by pumping the chip with increasing optical power. The laser was red-scanned from a wavelength of 1530–1570 nm. Before the suspension, we only observed a redshift in the resonant wavelength, as shown in Figure 4(b). In contrast, after the suspension, we observed optical bistability (see Figure 4(c)), which can be attributed to the reduced thermal conduction of the system. This showcases the importance of removing the BOX for PTS.

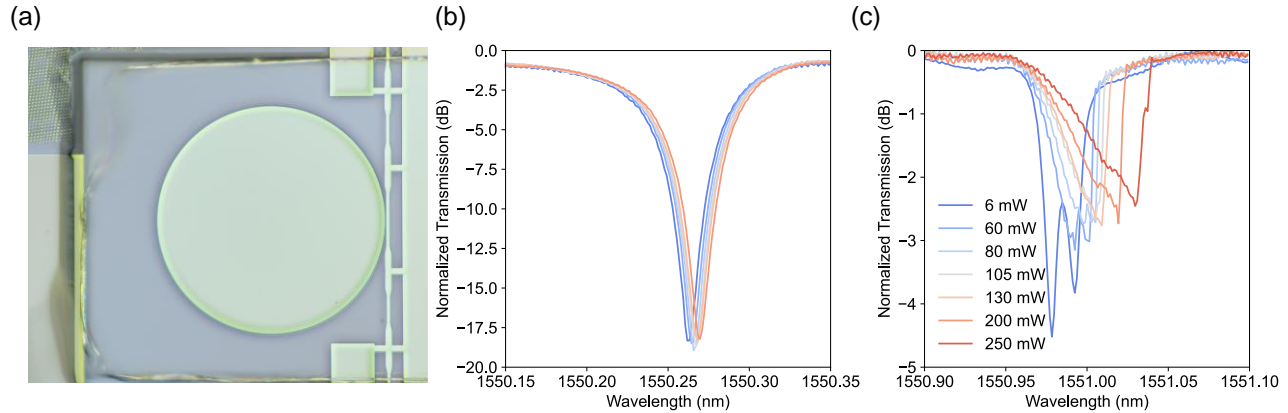


Figure 4. (a) Microscope image of microdisk resonator after suspension. Normalized transmission of microdisk resonator with radius = 65 μm and coupling gap = 150 nm for increasing input power (b) before suspension and (b) after suspension.

5. CONCLUSIONS

In summary, we have demonstrated a successful fabrication of microdisk resonators through a photonic foundry MPW run. Our measurement results indicated that the suspended microdisks can be used in performing PTS owing to their superior heat retention properties. Since SiN also gets attacked by BOE while removing the BOX, we aim to reduce the etch time while minimizing the mode field overlap with the BOX/Air interface. Therefore, we conclude that a SiN microdisk with a 30–65 μm radius will perform better despite the higher radiation losses.

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